

74F126

Quad buffers; 3-State

Rev. 4 — 23 January 2013

Product data sheet

1. General description

The 74F126 provides four non-inverting buffer/line drivers with 3-state outputs. The 3-state outputs (nY) are controlled by the output enable input (nOE). A LOW at nOE causes the outputs to assume a high-impedance OFF-state.

2. Features and benefits

- High impedance NPN base inputs for reduced loading (20 μ A in HIGH and LOW states)

3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
N74F126N	0 °C to +70 °C	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
N74F126D	0 °C to +70 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1



4. Functional diagram

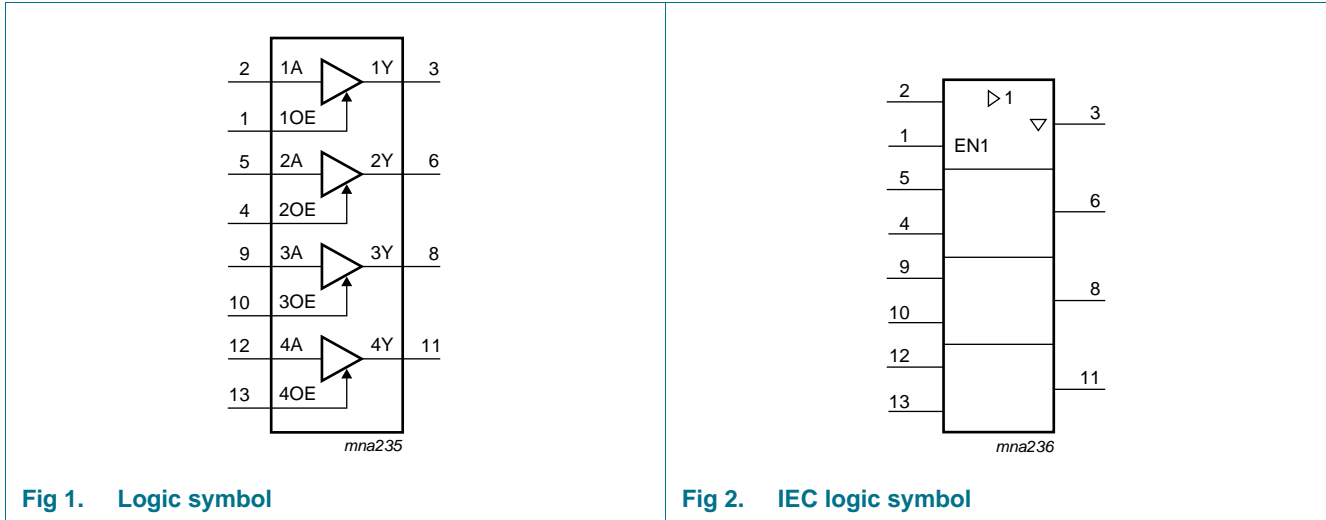


Fig 1. Logic symbol

Fig 2. IEC logic symbol

5. Pinning information

5.1 Pinning

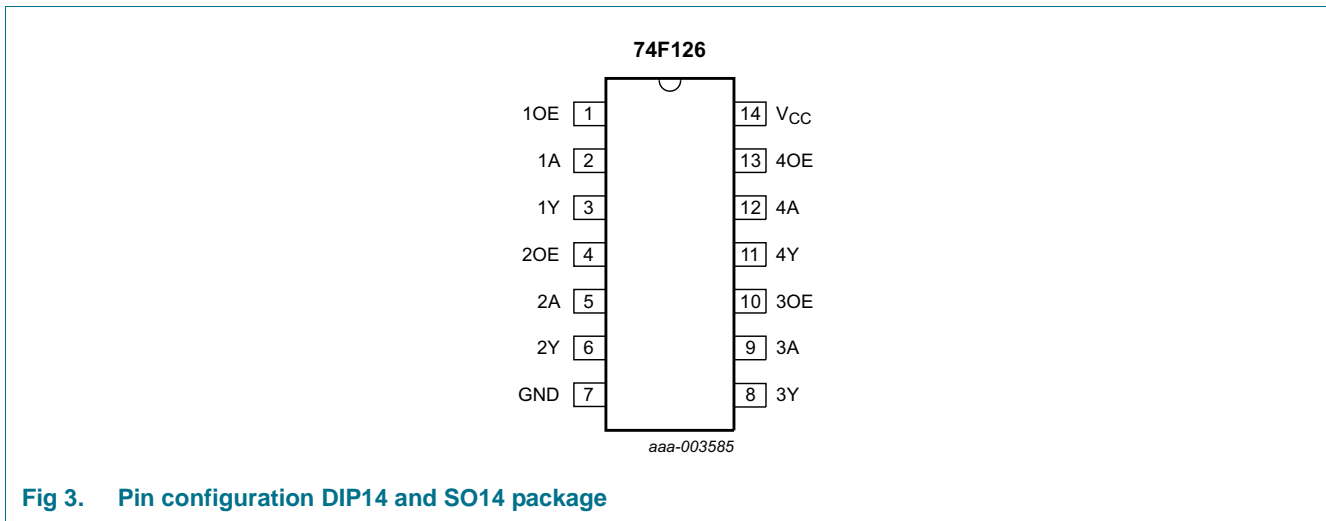


Fig 3. Pin configuration DIP14 and SO14 package

5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description	Unit load HIGH/LOW	Load value ^[1] HIGH/LOW
1OE to 4OE	1, 4, 10, 13	output enable input (active HIGH)	1.0/0.033	20 μ A/20 μ A
1A to 4A	2, 5, 9, 12	data input	1.0/0.033	20 μ A/20 μ A
1Y to 4Y	3, 6, 8, 11	data output	750/106.7	15 mA/64 mA
GND	7	ground (0 V)	-	-
V _{CC}	14	supply voltage	-	-

[1] One FAST Unit Load (UL) is defined as 20 μ A in HIGH state, 0.6 μ A in LOW state.

6. Functional description

Table 3. Function table^[1]

Control	Input	Output
nOE	nA	nY
H	L	L
	H	H
L	X	Z

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
V_I	input voltage		[1] -0.5	+7.0	V
V_O	output voltage	output in HIGH-state	[1] -0.5	V_{CC}	V
I_{IK}	input clamping current	$V_I < 0$ V	-30	+5	mA
I_O	output current	output in LOW-state	-	128	mA
T_{amb}	ambient temperature	in free air	[2] 0	70	$^{\circ}$ C
T_{stg}	storage temperature		-65	+150	$^{\circ}$ C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 $^{\circ}$ C.

8. Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_{IH}	HIGH-level input voltage		2.0	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.8	V
I_{IK}	input clamping current		-18	-	-	mA
I_{OH}	HIGH-level output current		-15	-	-	mA
I_{OL}	LOW-level output current		-	-	64	mA
T_{amb}	ambient temperature		0		70	$^{\circ}$ C

9. Static characteristics

Table 6. Static characteristics

Symbol	Parameter	Conditions	25 °C			0 °C to +70 °C		Unit	
			Min	Typ ^[1]	Max	Min	Max		
V _{IK}	input clamping voltage	V _{CC} = 4.5 V; I _{IK} = -18 mA	-1.2	-0.73	-	-1.2	-	V	
V _{OH}	HIGH-level output voltage	V _{CC} = 4.5 V; V _{IL} = 0.8 V; V _{IH} = 2.0 V I _{OH} = -3 mA	-	-	-	2.4	-	V	
		V _{CC} = ±10 %	-	-	-	2.7	-	V	
		V _{CC} = ±5 %	-	3.3	-	-	-	V	
		I _{OH} = -15 mA V _{CC} = ±10 %	-	-	-	2.0	-	V	
V _{OL}	LOW-level output voltage	V _{CC} = 4.5 V; V _{IL} = 0.8 V; V _{IH} = 2.0 V I _{OL} = 64 mA	-	-	-	-	0.55	V	
		V _{CC} = ±10 %	-	0.42	-	-	0.55	V	
		V _{CC} = ±5 %	-	-	-	-	-	V	
I _I	input leakage current	V _{CC} = 0 V; V _I = 7.0 V	-	-	-	-	100	μA	
I _{IH}	HIGH-level input current	V _{CC} = 5.5 V; V _I = 2.7 V	-	-	-	-	20	μA	
I _{IL}	LOW-level input current	V _{CC} = 5.5 V; V _I = 0.5 V	-	-	-	-20	-	μA	
I _{OZ}	OFF-state output current	V _{CC} = 5.5 V	-	-	-	-	-	50	μA
		V _O = 2.7 V	-	-	-	-	-	50	μA
		V _O = 0.5 V	-	-	-	-50	-	μA	
I _O	output current	V _{CC} = 5.5 V	[2]	-	-	-	-225	-100	mA
I _{CC}	supply current	V _{CC} = 5.5 V; V _I = GND or V _{CC}	-	20	-	-	-	30	mA
		outputs HIGH-state	-	32	-	-	-	48	mA
		outputs LOW-state	-	26	-	-	-	39	mA
		outputs OFF-state	-	-	-	-	-	-	-

[1] All typical values are measured at V_{CC} = 5 V.

[2] No more than one output should be tested at a time, and the duration of the test should not exceed one second.

10. Dynamic characteristics

Table 7. Dynamic characteristics

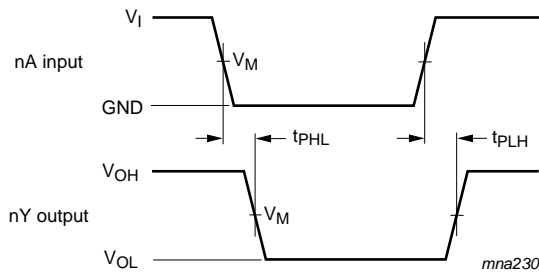
GND = 0 V. Test circuit is shown in [Figure 6](#).

Symbol	Parameter	Conditions	25 °C; V _{CC} = 5.0 V			0 °C to +70 °C; V _{CC} = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t _{PLH}	LOW to HIGH propagation delay	nA to nY; see Figure 4	2.0	4.0	6.5	2.0	7.0	ns
t _{PHL}	HIGH to LOW propagation delay	nA to nY; see Figure 4	3.0	5.5	8.0	3.0	8.5	ns
t _{PZH}	OFF-state to HIGH propagation delay	nOE to nY; see Figure 5	4.0	6.0	7.5	3.5	8.5	ns

Table 7. Dynamic characteristics ...continued
 GND = 0 V. Test circuit is shown in [Figure 6](#).

Symbol	Parameter	Conditions	25 °C; V _{CC} = 5.0 V			0 °C to +70 °C; V _{CC} = 5.0 V ± 0.5 V		Unit
			Min	Typ	Max	Min	Max	
t _{PZL}	OFF-state to LOW propagation delay	nOE to nY; see Figure 5	4.0	6.0	8.0	3.5	8.5	ns
t _{PHZ}	HIGH to OFF-state propagation delay	nOE to nY; see Figure 5	2.0	4.5	6.5	2.0	7.5	ns
t _{PLZ}	LOW to OFF-state propagation delay	nOE to nY; see Figure 5	3.0	5.5	7.5	3.0	8.0	ns

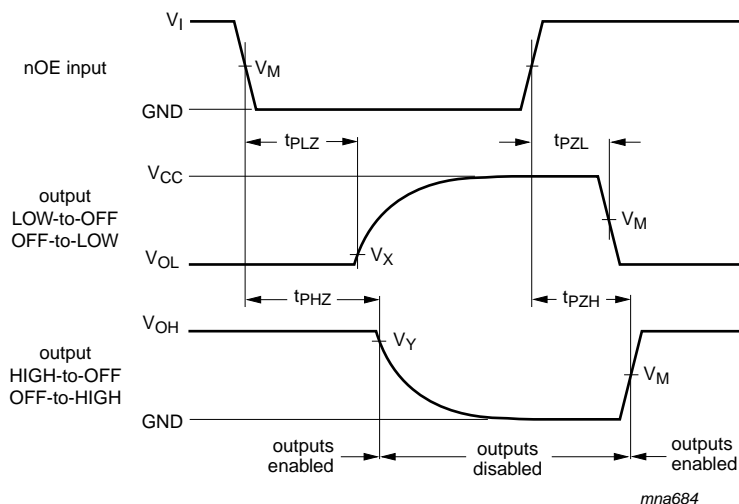
11. Waveforms



V_M = 1.5 V

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 4. Propagation delay input (nA) to output (nY)



V_M = 1.5 V

V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Fig 5. Enable and disable times

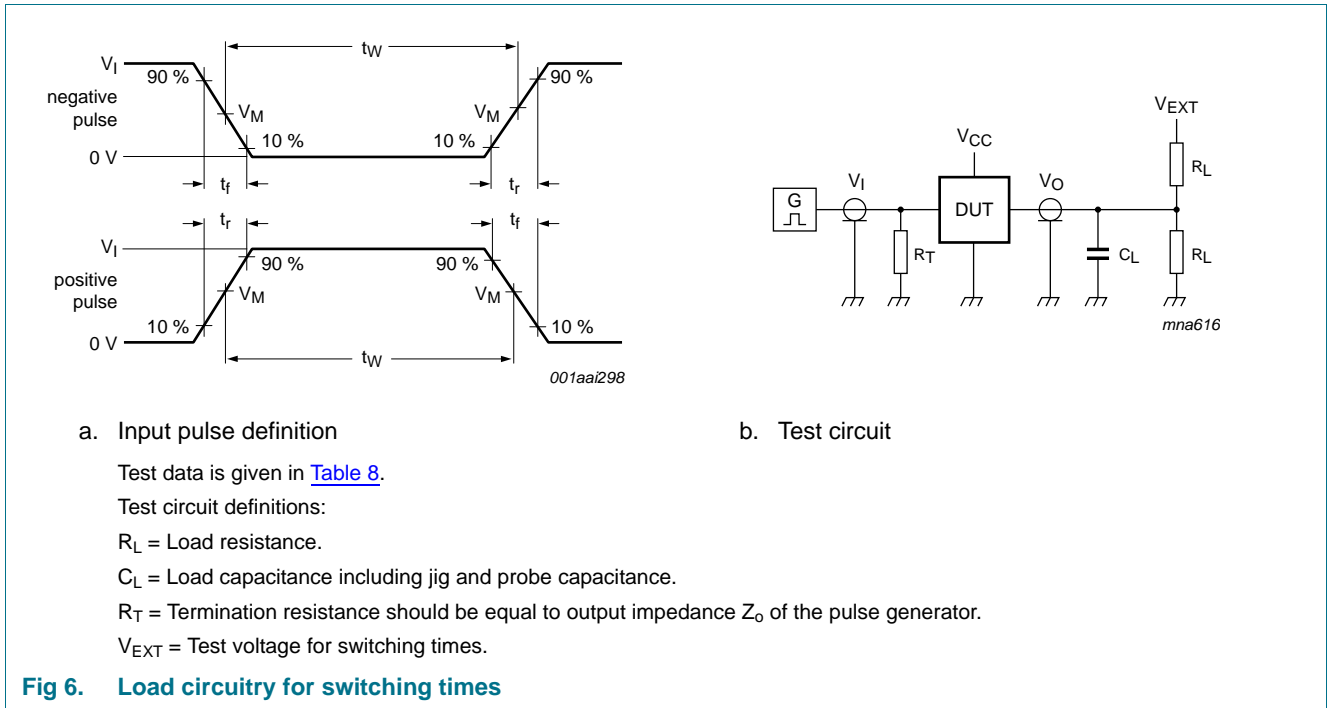


Table 8. Test data

Input				Load		V_{EXT}		
V_I	f_i	t_W	t_r, t_f	C_L	R_L	t_{PHL}, t_{PLH}	t_{PZH}, t_{PHZ}	t_{PZL}, t_{PLZ}
3.0 V	1 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	open	open	7.0 V

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

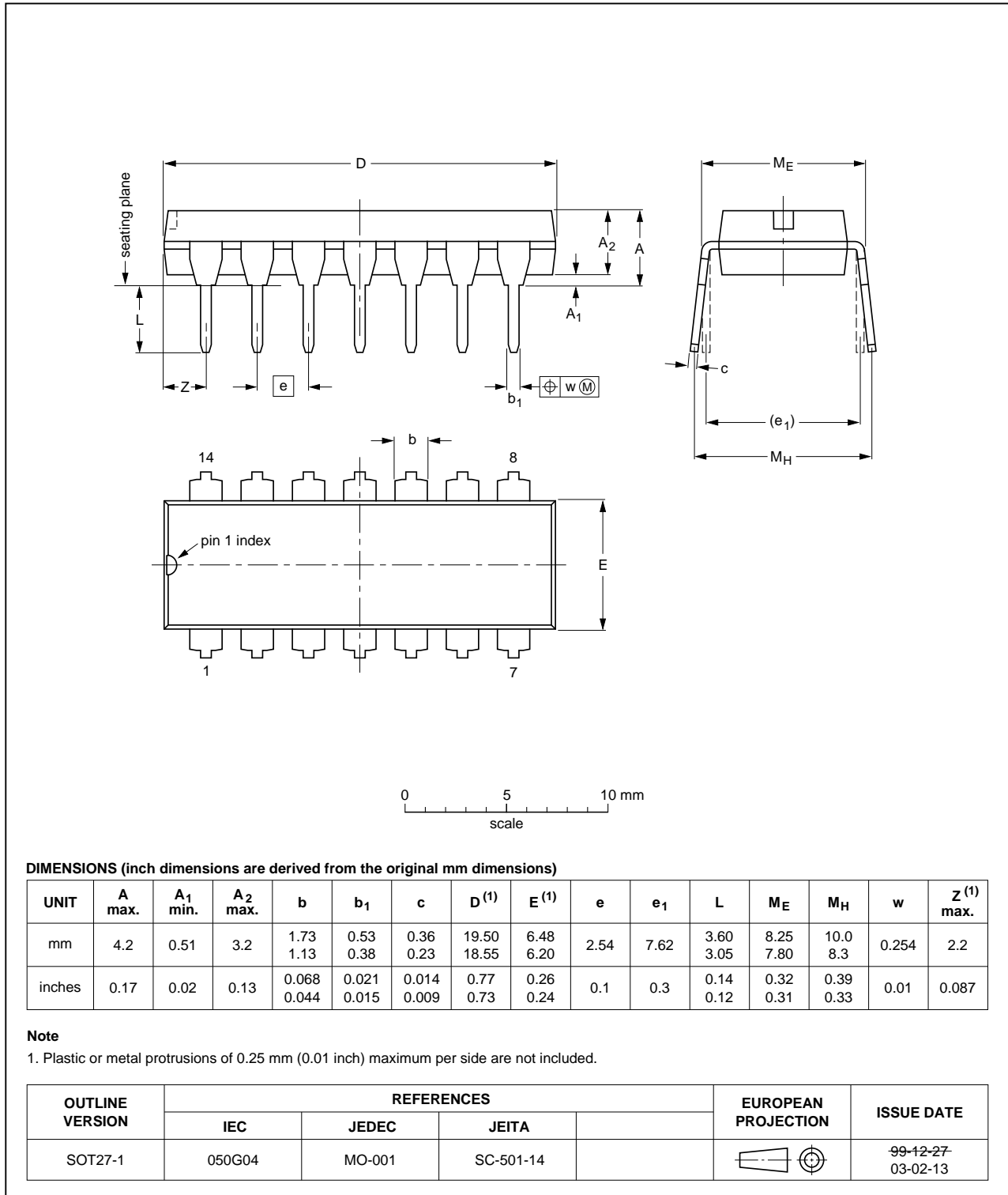


Fig 7. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

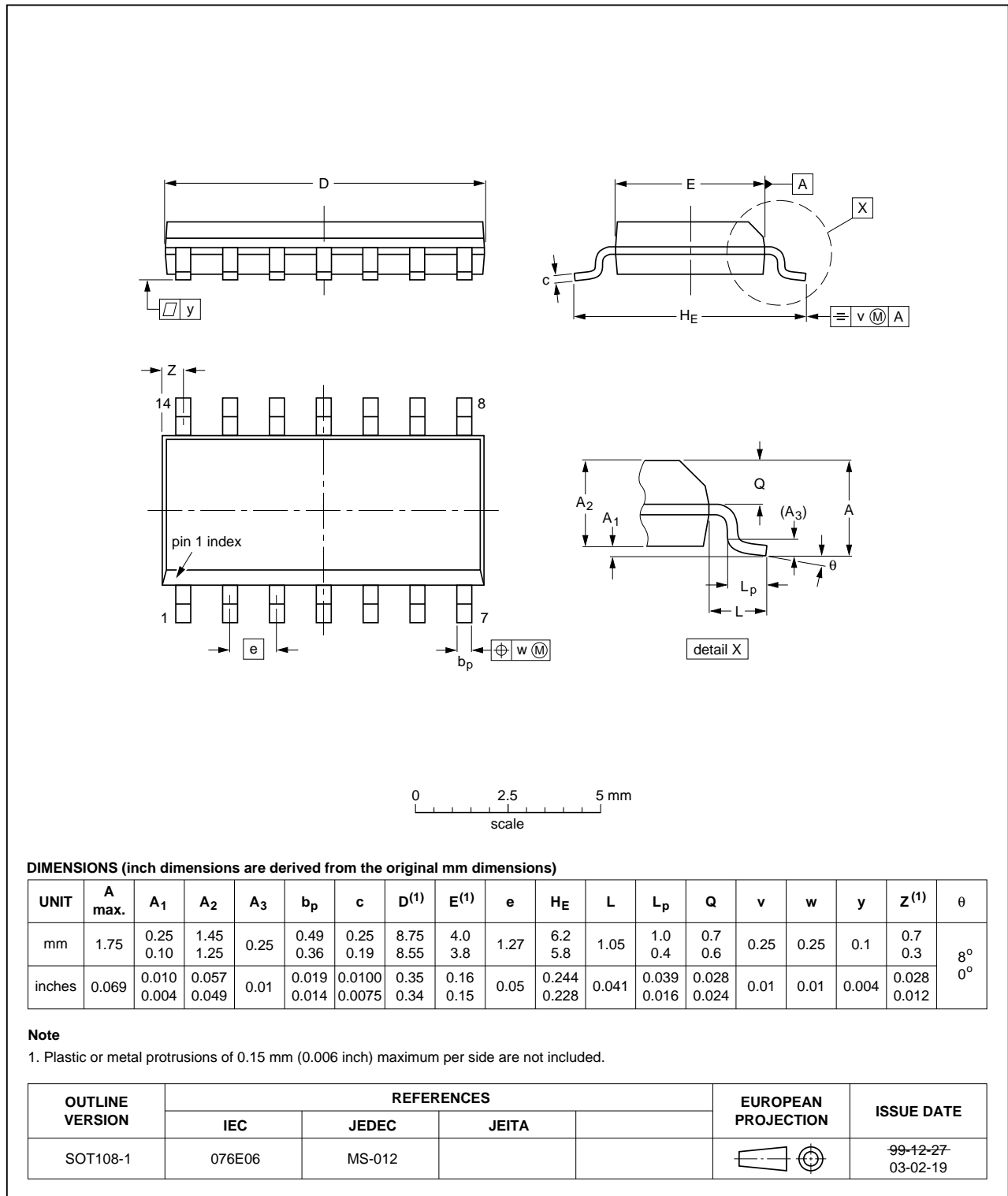


Fig 8. Package outline SOT108-1 (SO14)

13. Abbreviations

Table 9. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
LSTTL	Low-power Schottky Transistor-Transistor Logic
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
CDM	Charge-Device Model
TTL	Transistor-Transistor Logic

14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74F126 v.4	20130123	Product data sheet	-	74F126 v.3
Modifications:	<ul style="list-style-type: none"> • Features and benefits: Changed mA into μA (errata). 			
74F126 v.3	20130118	Product data sheet	-	74F126 v.2
Modifications:	<ul style="list-style-type: none"> • The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors. • Legal texts have been adapted to the new company name where appropriate. 			
74F126 v.2	19890328	Product data sheet	-	74F126 v.1

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Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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17. Contents

1	General description	1
2	Features and benefits	1
3	Ordering information	1
4	Functional diagram	2
5	Pinning information	2
5.1	Pinning	2
5.2	Pin description	2
6	Functional description	3
7	Limiting values	3
8	Recommended operating conditions	3
9	Static characteristics	4
10	Dynamic characteristics	4
11	Waveforms	5
12	Package outline	7
13	Abbreviations	9
14	Revision history	9
15	Legal information	10
15.1	Data sheet status	10
15.2	Definitions	10
15.3	Disclaimers	10
15.4	Trademarks	11
16	Contact information	11
17	Contents	12

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